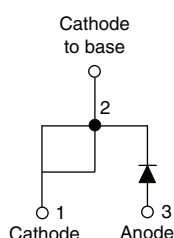
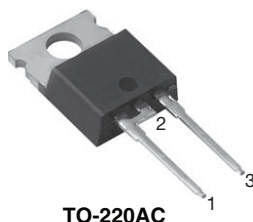


# HEXFRED® Ultrafast Soft Recovery Diode, 8 A



## FEATURES

- Ultrafast and ultrasoft recovery
- Very low  $I_{RRM}$  and  $Q_{rr}$
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization:  
for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

## DESCRIPTION

VS-HFA08TB120HN3 is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 8 A continuous current, the VS-HFA08TB120HN3 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to “snap-off” during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA08TB120HN3 is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

## PRODUCT SUMMARY

Package	TO-220AC
$I_{F(AV)}$	8 A
$V_R$	1200 V
$V_F$ at $I_F$	2.4 V
$t_{rr}$ typ.	28 ns
$T_J$ max.	150 °C
Diode variation	Single die

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		1200	V
Maximum continuous forward current	$I_F$	$T_C = 100\text{ °C}$	8	A
Single pulse forward current	$I_{FSM}$		130	
Maximum repetitive forward current	$I_{FRM}$		32	
Maximum power dissipation	$P_D$	$T_C = 25\text{ °C}$	73.5	W
		$T_C = 100\text{ °C}$	29	
Operating junction and storage temperature range	$T_J, T_{Stg}$		-55 to +150	°C

**ELECTRICAL SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	$V_{BR}$	$I_R = 100\text{ }\mu\text{A}$	1200	-	-	V
Maximum forward voltage	$V_{FM}$	$I_F = 8.0\text{ A}$	-	2.6	3.3	
		$I_F = 16\text{ A}$	-	3.4	4.3	
		$I_F = 8.0\text{ A}$ , $T_J = 125\text{ }^{\circ}\text{C}$	-	2.4	3.1	
Maximum reverse leakage current	$I_{RM}$	$V_R = V_R\text{ rated}$	-	0.31	10	$\mu\text{A}$
		$T_J = 125\text{ }^{\circ}\text{C}$ , $V_R = 0.8 \times V_R\text{ rated}$	-	135	1000	
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	11	20	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $di_F/dt = 200\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	28	-	ns
	$t_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	63	-	
	$t_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	106	-	
Peak recovery current	$I_{RRM1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	4.5	-	A
	$I_{RRM2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	6.2	-	
Reverse recovery charge	$Q_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	140	-	nC
	$Q_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	335	-	
Peak rate of recovery current during $t_b$	$di_{(rec)M}/dt1$	$T_J = 25\text{ }^{\circ}\text{C}$	-	133	-	$\text{A}/\mu\text{s}$
	$di_{(rec)M}/dt2$	$T_J = 125\text{ }^{\circ}\text{C}$	-	85	-	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	$T_{lead}$	0.063" from case (1.6 mm) for 10 s	-	-	300	$^{\circ}\text{C}$
Thermal resistance, junction to case	$R_{thJC}$		-	-	1.7	K/W
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC	HFA08TB120H			

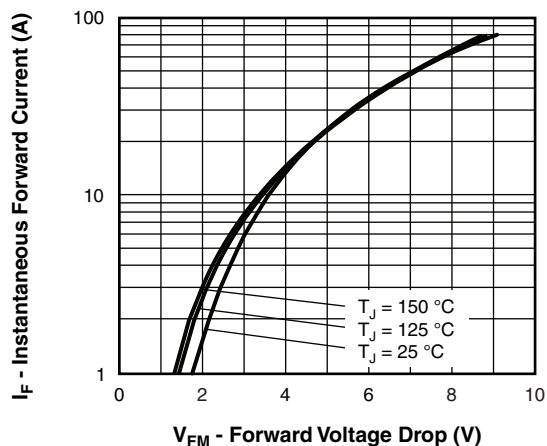


Fig. 1 - Maximum Forward Voltage Drop Characteristics

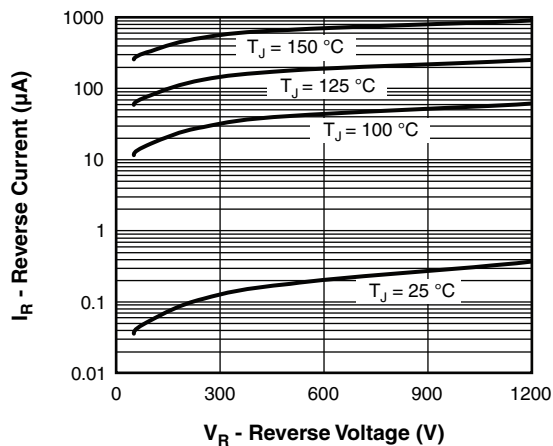


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

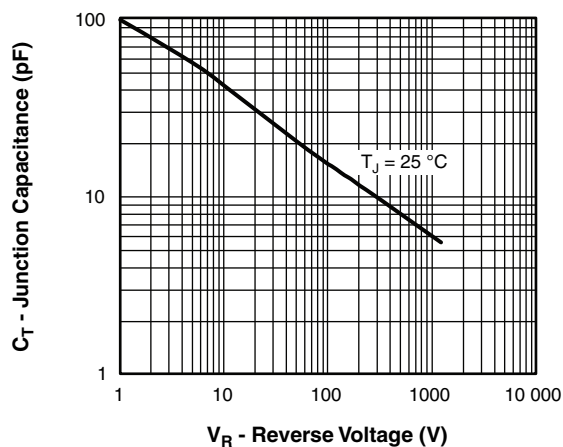
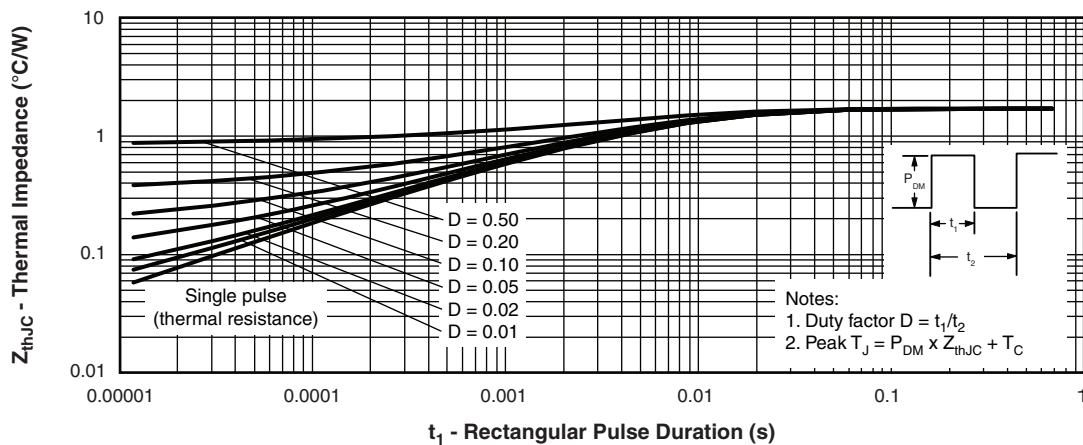


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

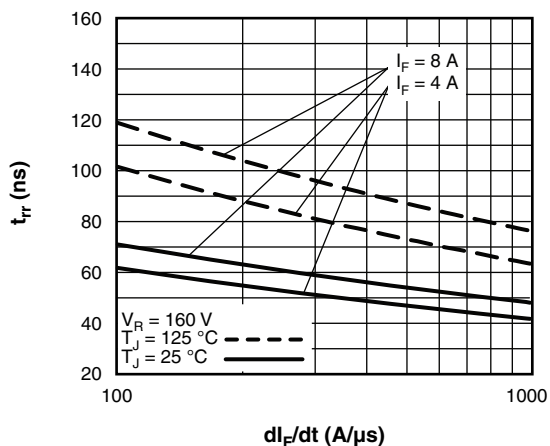
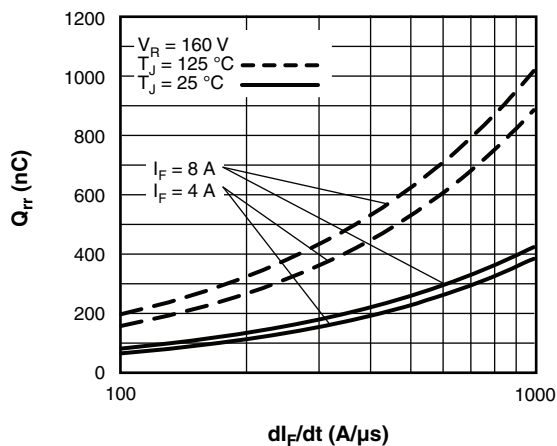
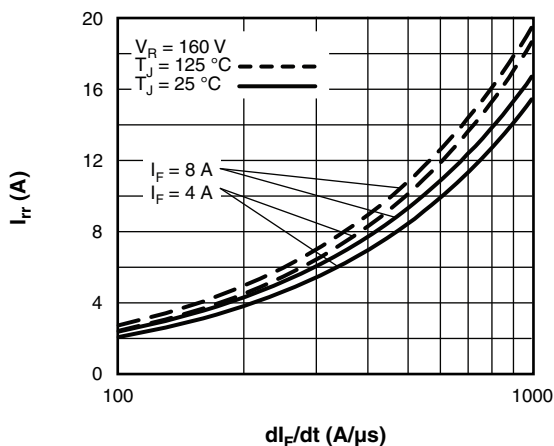
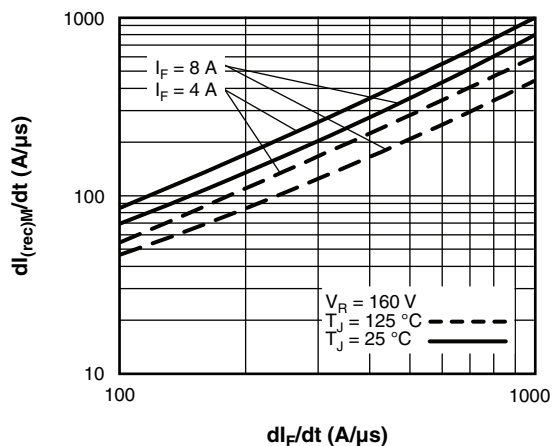
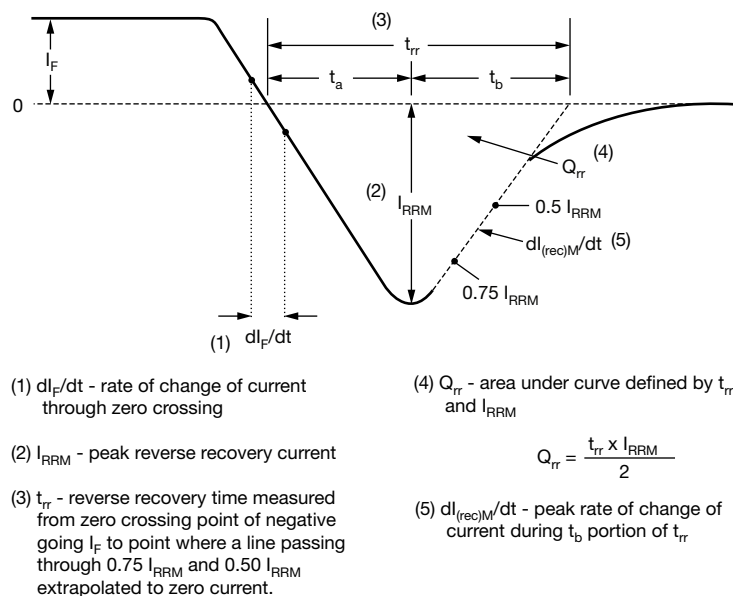

Fig. 5 - Typical Reverse Recovery Time vs.  $di_F/dt$ 

Fig. 7 - Typical Stored Charge vs.  $di_F/dt$ 

Fig. 6 - Typical Recovery Current vs.  $di_F/dt$ 

Fig. 8 - Typical  $di_{(rec)M}/dt$  vs.  $di_F/dt$ 


Fig. 9 - Reverse Recovery Waveform and Definitions



## ORDERING INFORMATION TABLE

Device code	<b>VS-</b>	<b>HF</b>	<b>A</b>	<b>08</b>	<b>TB</b>	<b>120</b>	<b>H</b>	<b>N3</b>
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (08 = 8 A)
- 5** - Package:  
TB = TO-220AC
- 6** - Voltage rating (120 = 1200 V)
- 7** - H = AEC-Q101 qualified
- 8** - Environmental digit:  
N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA08TB120HN3	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95221">www.vishay.com/doc?95221</a>
Part marking information	<a href="http://www.vishay.com/doc?95068">www.vishay.com/doc?95068</a>



### TO-220AC

**DIMENSIONS** in millimeters and inches



Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
E	10.11	10.51	0.398	0.414	3, 6

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
e1	4.88	5.28	0.192	0.208	
H1	5.84	6.86	0.230	0.270	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
L3	1.78	2.13	0.070	0.084	
L4	0.76	1.27	0.030	0.050	2
Ø P	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	

#### Notes

- Dimensioning and tolerancing as per ASME Y14.5M-1994
- Lead dimension and finish uncontrolled in L1
- Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Dimension b1, b3 and c1 apply to base metal only
- Controlling dimension: inches
- Thermal pad contour optional within dimensions E, H1, D2 and E1
- Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



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